



# SOT238-4

plastic, thermally enhanced quad; flat non-leaded package;  
52 terminals; 1.27 mm pitch; 19.125 mm x 19.125 mm x 4.385  
mm body

15 December 2016

Package information

## 1. Package summary

Terminal position code	Q (quad)
Package type descriptive code	PLCC
Package type industry code	PLCC52
Package style descriptive code	PLCC (plastic leaded chip carrier)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	5-8-2016
Manufacturer package code	98ASB42600B

Table 1. Package summary

Symbol	Parameter		Min	Typ	Nom	Max	Unit
D	package length		19.05	-	19.125	19.2	mm
E	package width		19.05	-	19.125	19.2	mm
A	seated height		4.2	-	4.385	4.57	mm
e	nominal pitch		-	-	1.27	-	mm
n <sub>2</sub>	actual quantity of termination		-	-	52	-	



plastic, thermally enhanced quad; flat non-leaded package; 52 terminals; 1.27 mm pitch; 19.125 mm x 19.125 mm x 4.385 mm body

2. Package outline

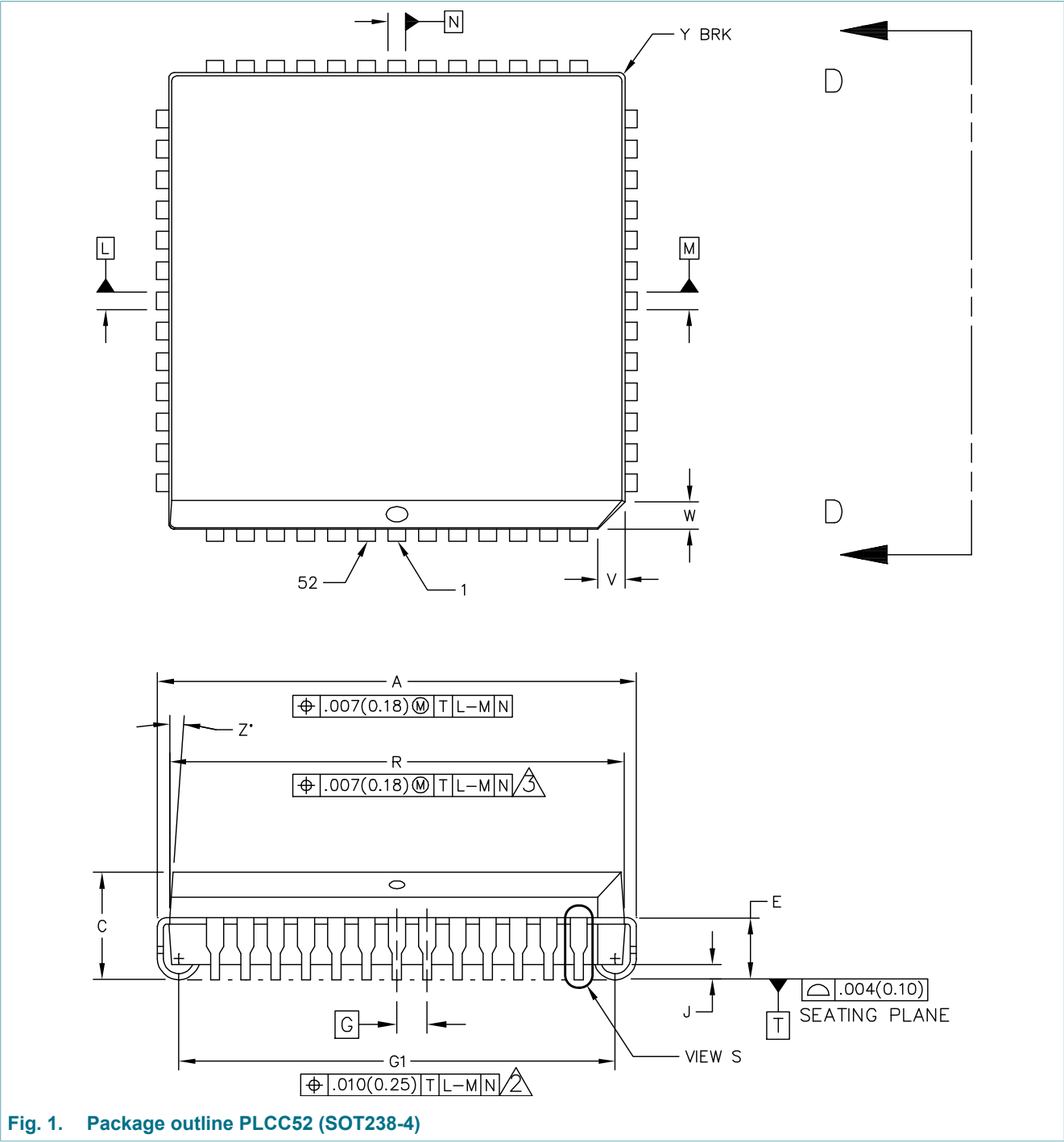


Fig. 1. Package outline PLCC52 (SOT238-4)

plastic, thermally enhanced quad; flat non-leaded package; 52 terminals; 1.27 mm pitch; 19.125 mm x 19.125 mm x 4.385 mm body

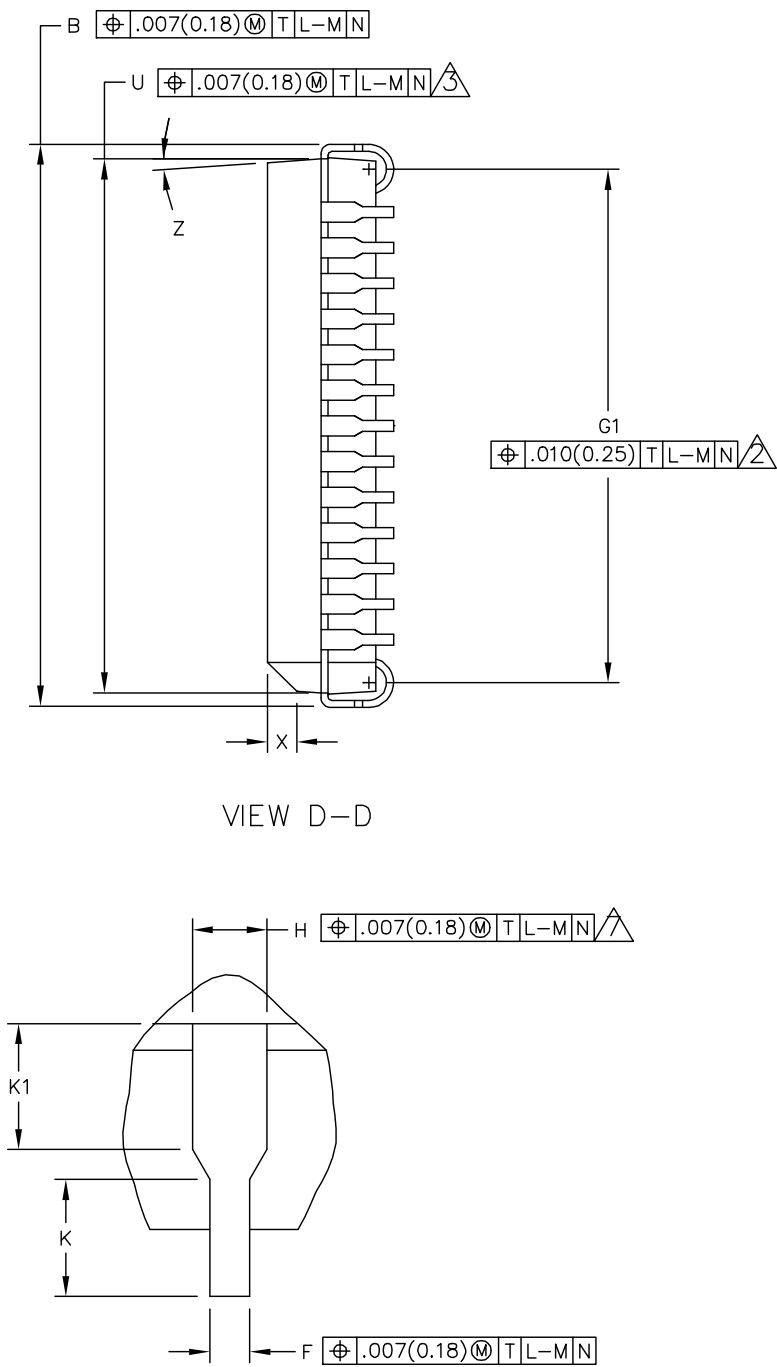


Fig. 2. Package outline dt1 PLCC52 (SOT238-4)

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DIM	MILLIMETERS		INCHES		DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX		MIN	MAX	MIN	MAX
A	19.94	20.19	0.785	0.795					
B	19.94	20.19	0.785	0.795					
C	4.20	4.57	0.165	0.180					
E	2.29	2.79	0.090	0.110					
F	0.33	0.48	0.013	0.019					
G	1.27	BSC	0.050	BSC					
H	0.66	0.81	0.026	0.032					
J	0.51	---	0.020	---					
K	0.64	---	0.025	---					
R	19.05	19.20	0.750	0.756					
U	19.05	19.20	0.750	0.756					
V	1.07	1.21	0.042	0.048					
W	1.07	1.21	0.042	0.048					
X	1.07	1.42	0.042	0.056					
Y	---	0.50	---	0.020					
Z	2°	10°	2°	10°					
G1	18.04	18.54	0.710	0.730					
K1	1.02	---	0.040	---					

Fig. 3. Package outline dt2 PLCC52 (SOT238-4)




- NOTES:
- DATUMS L, M AND N DETERMINED WHERE TOP OF LEAD SHOULDER EXITS PLASTIC BODY AT MOLD PARTING LINE.
  -  DIMENSION TRUE POSITION TO BE MEASURED AT DATUM T, SEATING PLANE.
  -  DIMENSIONS DO NOT INCLUDE MOLD FLASH. ALLOWABLE MOLD FLASH IS .010(0.25) PER SIDE.
  - DIMENSIONING AND TOLERANCING PER ASME Y14.5 – 1994.
  - CONTROLLING DIMENSION: INCH.
  - THE PACKAGE TOP MAY BE SMALLER THAN THE PACKAGE BOTTOM BY UP TO .012(0.30). DIMENSIONS R AND U ARE DETERMINED AT THE OUTERMOST EXTREMES OF THE PLASTIC BODY EXCLUSIVE OF MOLD FLASH. TIE BAR BURRS, GATE BURRS AND INTERLEAD FLASH, BUT INCLUDING ANY MISMATCH BETWEEN THE TOP AND BOTTOM OF THE PLASTIC BODY.
  -  DIMENSION DOES NOT INCLUDE DAMBAR PROTRUSION OR INTRUSION. THE DAMBAR PROTRUSION (S) SHALL NOT CAUSE THE DIMENSION TO BE GREATER THAN .037(0.94). THE DAM BAR INTRUSION (S) SHALL NOT CAUSE THE DIMENSION TO BE SMALLER THAN .025(0.63).

Fig. 4. Package outline nt PLCC52 (SOT238-4)

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### 3. Legal information

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